Charge collection and trapping effects in n- and p-type epitaxial silicon diodes after proton irradiation

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GEFÖRDERT VOM

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In the framework of the CERN RD50 Collaboration

Introduction

- Trapping: most limiting factor at S-LHC fluences
 - Usually described by an effective trapping time constant τ_{eff}:
 - Previous measurements* for FZ/Cz material at low fluences:

$$\begin{split} \textbf{N(t)} &= \textbf{N}_{0} \; \textbf{exp}(-\frac{\textbf{t}}{\tau_{\text{eff}}}) \\ & \frac{1}{\tau_{\text{eff}}} = \beta \; \Phi_{\text{eq}} \end{split}$$

- *cf. G.Kramberger's PhD thesis
- What happens in epitaxial material, at high fluences and high voltages?
- Last RD50 workshop (Nov 08): Results for n-type EPI diodes presented
 - Time-resolved TCT signals (670nm laser) for 150µm EPI
 - CCM $\rightarrow \beta_e$ in EPI similar to FZ/Cz material
 - CCE (α) >1 \rightarrow avalanche effects
 - CCE simulation underestimates measurements \rightarrow modified trapping description needed
- Here:
 - Update for further fluence points
 - p-type investigated (τ_{eff}, CCE (α))
 - Comparison of CCE for different charge injection distributions (670nm, 1060nm, α)



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Overview on investigated diodes

- Epitaxial Si pad-detectors on Cz-substrate produced by ITME/CiS
- Size: 5 x 5 mm² and 2.5 x 2.5 mm²
- n-type: 75 μm, 100 μm and 150 μm thickness; Standard (ST) and oxygen enriched (DO, diffusion for 24h at 1100°C) material
- p-type: only 75 µm ST material
- 24 GeV/c-proton-irradiation (CERN PS), $\Phi_{eq} = 1 \times 10^{14} 1 \times 10^{16} \text{ cm}^{-2}$

Material	d	Wafer	Orientation	N _{off} 0	[0]	Oxygen Concentration Depth Profile of EPI 75µm
	[µ m]			[10 ¹² cm ^{-3]}	[10 ¹⁶ cm ⁻³]	
n-EPI ST 75	74	8364-03	<111>	26	9.3	6 75 ST
n-EPI DO 75	72	8364-07	<111>	26	60.0	• 75 DO
n-EPI ST 100	102	261636-05	<100>	15	5.4	
n-EPI DO 100	99	261636-01	<100>	15	28.0	Succession of the second
n-EPI ST 150	147	261636-13	<100>	8.8	4.5	
n-EPI DO 150	152	261636-09	<100>	8	14.0	EPI layer ← Cz substrate
p-EPI ST 150	149	271713-26	<100>	13		

TCT electron signals (n-type)



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TCT hole signals (p-type)



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Determination of τ_{eff}

Results from Charge Correction Method:

 Also in Epi: If assumed to be constant at each fluence, trapping probability found to be fluence-proportional

$$\frac{1}{\tau_{\text{eff,e/h}}} = \beta_{\text{e/h}} \Phi_{\text{eq}}$$

 Damage parameter β: similar values as in FZ*

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*cf. G.Kramberger's PhD thesis



	n-type	p-type
	$\beta_{e} \left[10^{-16} \text{cm}^2 \text{ns}^{-1} \right]$	$\beta_{h} \left[10^{-16} \text{cm}^2 \text{ns}^{-1} \right]$
EPI-ST	5.3 ± 0.4	7.4 ± 0.9
EPI-DO	4.5 ± 0.5	
EPI comb.	5.0 ± 0.3	7.4 ± 0.9
cf. FZ*	5.1	6.5

CCE as a function of bias voltage



Almost saturation for low fluences at high voltages

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 n-type: Stronger increase for high fluences (avalanche effects) p-type: approximately linear increase for Φ_{eq}≥2.7x10¹⁵ cm⁻²

CCE as a function of fluence



- CCE degrades with fluence, but deceleration at high fluences (due to avalanche effects?)
- CCE improves for decreasing thickness as t_c decreases (smaller distance, higher field)
- No significant difference between ST and DO material

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• CCE of p-type lower than CCE of n-type (v_{dr} and τ_{eff} smaller for holes)

Comparison CCE (670nm, 1060nm laser, α)



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- Different charge injection distributions:
 - 5.8MeV α: range 26µm; well-defined charge deposition → small normalisation error (~3%)
 - 670nm: $\lambda_{abs}=3\mu m$; laser intensity variations \rightarrow larger normalisation error (up to 10%)
 - 1060nm : $\lambda_{abs}=1mm$; laser intensity variations \rightarrow larger normalisation error (up to 10%)
- Simulation with τ_{eff}=const underestimates measured data in all cases; voltage-dependent behaviour not well reproduced
- But relative position between CCE of different distributions well reproduced
- U-dependent τ_{eff} fits better:

$$\tau_{eff,e} = \tau_0(U_{dep}) + \tau_1 \frac{(U - U_{dep})}{100V}$$

Comparison CCE (670nm, 1060nm laser, α)



- Smaller penetration depth → stronger charge multiplication (more charge deposited in high-field region; more e instead of h)
- CCE(670nm)- and IV-curves almost identical at high voltages (for 75µm, 10¹⁶cm⁻²)

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Summary

- 670nm laser: time-resolved TCT signals in Epi 150µm
 - n-type: no type inversion; p-type: type inversion for $\Phi_{eq} \ge 3.7 \times 10^{14} \text{ cm}^{-2}$
 - Double Junction already at low fluences in p-type
 - CCM -> trapping probability similar to FZ
- CCE determination:
 - CCE_{e,n-type}>CCE_{h,p-type}
 - Avalanche effect strongest for small penetration depth (CCE>7 for 75µm!)
- Comparison CCE measurements simulation
 - Simulation underestimates measurements for all charge injection distributions
 - Relative position between different charge injection distributions well reproduced
 - Better agreement if U-dependent τ_{eff} assumed

BACKUP SLIDES

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Depletion Voltage (from CV at 10 kHz)

Stable Damage:



New Laser-TCT Setup



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Alpha-TCT Setup



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Simulation details

Integrated induced charge for e-h pair deposited at x_0 (e + h contribution):

$$Q_{x_0} = \frac{Q_{0,x_0}}{d} \left[\int_{x_0}^d \exp\left(-\frac{t(x)}{\tau_{eff,e}}\right) dx - \int_{x_0}^0 \exp\left(-\frac{t(x)}{\tau_{eff,h}}\right) dx \right] \quad \text{with} \quad t(x) = \int_{x_0}^x \frac{1}{v_{dr} \left(E\left(x'\right)\right)} dx$$

Drift velocity parameterisation (C.Jacobini, Sol.State El., Vol. 20, 1977):

$v_{dr} = \frac{\mu_0 E}{\left(1 + \left(\frac{\mu_0 E}{v_{sat}}\right)^\beta\right)^{1/\beta}}$	with	$\begin{array}{rcl} \mu_{0,e} &= \\ v_{sat,e} &= \\ \beta_{e} &= \end{array}$	$\begin{array}{l} 1.51\times 10^9 \cdot T^{-2.42} \frac{cm^2}{Vs} \\ 1.53\times 10^9 \cdot T^{-0.87} \frac{cm}{s} \\ 2.57\times 10^{-2} \cdot T^{0.66} \end{array}$	\Rightarrow \Rightarrow \Rightarrow	$\begin{array}{ll} 1605.4 \frac{cm^2}{Vs} & \text{ at } 294K \\ 1.09 \times 10^7 \frac{cm}{s} \\ 1.09 \end{array}$
		$\begin{array}{rcl} \mu_{0,h} & = \\ v_{sat,h} & = \\ \beta_h & = \end{array}$	$\begin{array}{l} 1.31 \times 10^8 \cdot T^{-2.2} \frac{cm^2}{Vs} \\ 1.62 \times 10^8 \cdot T^{-0.52} \frac{cm}{s} \\ 0.46 \cdot T^{0.17} \end{array}$	${\Rightarrow} {\Rightarrow}$	$486.3 \frac{cm^2}{Vs}$ $0.84 \times 10^7 \frac{cm}{s}$ 1.21

Linear electric-field approximation:

$$E(x) = \frac{1}{d} \left[U_{dep} \left(\frac{2x}{d} - 1 \right) - U \right], \qquad U \ge U_{dep}$$

Integration over all positions where e-h pairs were created:

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$$Q_{total} = \int_0^d Q_{x_0} dx_0$$

Charge deposition as a function of detector depth $Q_{0,x0}$ calculated by SRIM for 5.8 MeV α -particles

Creation of e-h Pairs as a Function of Detector Depth



Comparison: Simulation ↔ Measured data

n-type, α

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- Simulation with const. τ_{eff} underestimates measured data (even if $v_{dr} = v_{sat}$ assumed everywhere $\Rightarrow v_{dr}(E)$ and E(x) model uncertainties are not the reason)
- Possible Reasons: avalanche effects (only at high U, Φ), detrapping, non-const. τ_{eff} (variable cross section? non-const. occupation, e.g. due to trap filling at high I_{rev}?)
- First try: voltage-dependent $\tau_{eff}^* \Rightarrow$ good fits possible

* cf. L.Beattie NIM A 421 (1999), 502

Results from U-dependent τ_{eff} fit of CCE(U)

$$\tau_{eff,e} = \tau_0(U_{dep}) + \tau_1 \frac{(U - U_{dep})}{100V}$$

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